



Advance Product Change Notification

202003037A

Issue Date: 05-Jun-2020

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.



QUALITY

Change Category

- | | | | | |
|--|--|--|--|---|
| <input checked="" type="checkbox"/> Wafer Fab Process | <input checked="" type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input checked="" type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input checked="" type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input checked="" type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

Replacement of the AMR Sensor Chip for KMZ60&KMZ60/E

Description of Change

Production of AMR sensor chip for KMZ60 and KMZ60/E will be transferred from 150mm line at Nexperia, Hamburg to 200mm line at Vanguard, Taiwan. However, design and dimension of the AMR sensor chip will not be changed.

Wafertest is currently part of AMR sensor production at Nexperia and in future, will be performed at test center of NXP Semiconductors Bangkok, Thailand.

The diameter of the bond wires will be reduced to 20 µm.

Package, pinning and electrical behavior remain unchanged.

For more details see attached document "Changes for KMZ60, KMZ60/E"

Reason for Change

Securing future delivery capability

Identification of Affected Products

Top side marking

Product Availability

Sample Information

Samples are available upon request

Samples are available upon request

Not qualified engineering samples are available upon request. Qualified Samples will be available with the final PCN.

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification Issue Date	Effective Date	Title
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202001019A	20-Feb-2020	Replacement of the AMR Sensor Chip for KMZ49&KMZ43TR
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Timing and Logistics

The Self Qualification Report will be ready on 30-Sep-2020.

The Final PCN is planned to be issued on: 30-Sep-2020.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 05-Jul-2020.

About NXP Semiconductors

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Affected Part Number

KMZ60,115

